



### 60V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

# **Product Summary**

| BV <sub>DSS</sub> | R <sub>DS(ON)</sub> MAX       | I <sub>D MAX</sub><br>T <sub>C</sub> = +25°C |
|-------------------|-------------------------------|--|
| 60V               | $14m\Omega @ V_{GS} = 10V$    | 50.5A  |
|                   | $21m\Omega$ @ $V_{GS} = 4.5V$ | 41.2A  |

## **Features**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH6012LPSWQ is suitable for automotive applications requiring specific change control and is AEC-Q101 qualified, is PPAP capable, and is manufactured in IATF16949:2016 certified facilities.

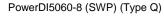
# **Description and Applications**

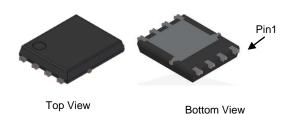
This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

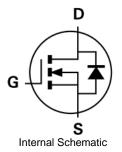
- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

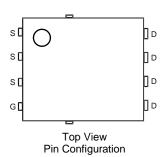
## **Mechanical Data**

- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Weight: 0.097 grams (Approximate)









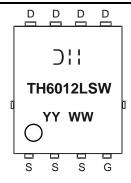
#### Ordering Information (Note 4)

| Part Number      | Case                         | Packaging           |
|------------------|------------------------------|---------------------|
| DMTH6012LPSWQ-13 | PowerDI5060-8 (SWP) (Type Q) | 2,500 / Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



D!! = Manufacturer's Marking
TH6012LSW = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 19 = 2019)
WW = Week Code (01 to 53)

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# **Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

| Characteristic  | Symbol                  | Value            | Unit |    |  |
|---|-------------------------|------------------|------|----|--|
| Drain-Source Voltage  |                         | $V_{DSS}$        | 60   | V  |  |
| Gate-Source Voltage   |                         | $V_{GSS}$        | ±20  | V  |  |
| Continuous Pusis Coment V 40V (Note 5)                          | T <sub>A</sub> = +25°C  | ı                | 11.5 | A  |  |
| Continuous Drain Current, V <sub>GS</sub> = 10V (Note 5)        | T <sub>A</sub> = +100°C | I <sub>D</sub>   | 8.1  |    |  |
| Continuous Pusis Coment V 40V (Note C)                          | T <sub>C</sub> = +25°C  | ı                | 50.5 | ^  |  |
| Continuous Drain Current, V <sub>GS</sub> = 10V (Note 6)        | T <sub>C</sub> = +100°C | - I <sub>D</sub> | 35.7 | A  |  |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)              | I <sub>DM</sub>         | 200              | Α    |    |  |
| Maximum Continuous Body Diode Forward Current (Note 6)          | I <sub>S</sub>          | 50               | Α    |    |  |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%) |                         | I <sub>SM</sub>  | 200  | Α  |  |
| Avalanche Current, L=0.1mH                                      |                         | I <sub>AS</sub>  | 12.6 | Α  |  |
| Avalanche Energy, L=0.1mH                                       |                         | E <sub>AS</sub>  | 7.9  | mJ |  |

# **Thermal Characteristics**

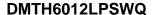
| Characteristic                                   |                      | Symbol           | Value       | Unit |
|--|----------------------|------------------|-------------|------|
| Total Power Dissipation (Note 5)                 | $T_A = +25^{\circ}C$ | P <sub>D</sub>   | 2.8         | W    |
| Thermal Resistance, Junction to Ambient (Note 5) |                      | $R_{\theta JA}$  | 54          | °C/W |
| Total Power Dissipation (Note 6)                 | $T_C = +25^{\circ}C$ | $P_{D}$          | 53.6        | W    |
| Thermal Resistance, Junction to Case (Note 6)    |                      | $R_{	heta JC}$   | 2.8         | °C/W |
| Operating and Storage Temperature Range          |                      | $T_{J_1}T_{STG}$ | -55 to +175 | °C   |

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

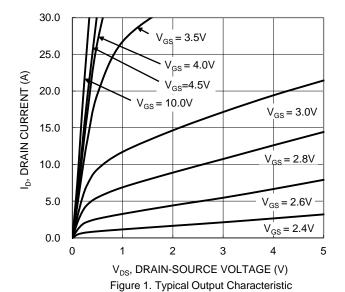
| Characteristic                             | Symbol              | Min | Тур  | Max  | Unit | Test Condition   |
|--|---------------------|-----|------|------|------|--|
| OFF CHARACTERISTICS (Note 7)               | , ,                 |     |      |      |      |  |
| Drain-Source Breakdown Voltage             | BV <sub>DSS</sub>   | 60  | _    | _    | V    | $V_{GS} = 0V, I_D = 1mA$                                 |
| Zero Gate Voltage Drain Current            | I <sub>DSS</sub>    | _   | _    | 1    | μA   | V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V              |
| Gate-Source Leakage                        | I <sub>GSS</sub>    | _   | _    | ±100 | nA   | $V_{GS} = \pm 20V, V_{DS} = 0V$                          |
| ON CHARACTERISTICS (Note 7)                |                     | •   | •    | •    |      |  |
| Gate Threshold Voltage                     | $V_{GS(TH)}$        | 1   | _    | 2.3  | V    | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$                     |
| Otatia Busin Casusa On Basintana           |                     | _   | 10.6 | 14   |      | V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A              |
| Static Drain-Source On-Resistance          | R <sub>DS(ON)</sub> |     | 14.8 | 21   | mΩ   | $V_{GS} = 4.5V, I_D = 10A$                               |
| Diode Forward Voltage                      | V <sub>SD</sub>     | _   | 0.7  | 1.2  | V    | V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A                |
| DYNAMIC CHARACTERISTICS (Note 8)           |                     | •   | •    | •    |      |  |
| Input Capacitance                          | C <sub>iss</sub>    | _   | 785  | _    |      | V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V,<br>f = 1MHz |
| Output Capacitance                         | Coss                | _   | 281  | _    | pF   |  |
| Reverse Transfer Capacitance               | C <sub>rss</sub>    | _   | 27   | _    |      |  |
| Gate Resistance                            | $R_g$               | _   | 1.5  | _    | Ω    | $V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$               |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) | Qq                  | _   | 7.3  | _    |      | V <sub>DS</sub> = 30V, I <sub>D</sub> = 10A              |
| Total Gate Charge (V <sub>GS</sub> = 10V)  | Qq                  | _   | 13.6 | _    | -0   |  |
| Gate-Source Charge                         | Q <sub>gs</sub>     | _   | 2.2  | _    | nC   |  |
| Gate-Drain Charge                          | $Q_{gd}$            | _   | 3.4  | _    |      |  |
| Turn-On Delay Time                         | t <sub>D(ON)</sub>  | _   | 3.2  | _    |      | $V_{DD} = 30V, V_{GS} = 10V,$                            |
| Turn-On Rise Time                          | t <sub>R</sub>      | _   | 4.4  | _    | ns   |  |
| Turn-Off Delay Time                        | t <sub>D(OFF)</sub> | _   | 14.7 | _    | ns   | $I_D = 10A$ , $R_g = 6\Omega$                            |
| Turn-Off Fall Time                         | t <sub>F</sub>      | _   | 8.5  | _    |      | _  |
| Body Diode Reverse Recovery Time           | t <sub>RR</sub>     | _   | 23.0 | _    | ns   | 1 400 4:/4+ 4000/  |
| Body Diode Reverse Recovery Charge         | $Q_{RR}$            | _   | 14.1 | _    | nC   | I <sub>F</sub> = 10A, di/dt = 100A/μs                    |

5. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

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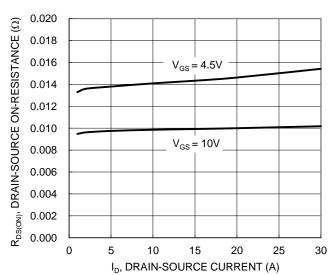


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

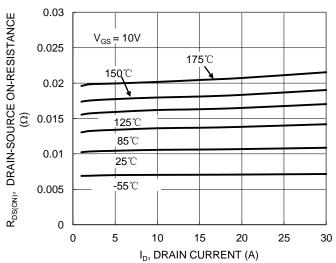


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

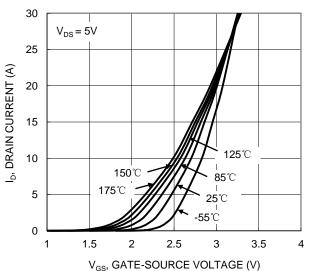


Figure 2. Typical Transfer Characteristic

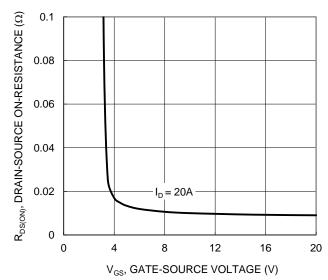
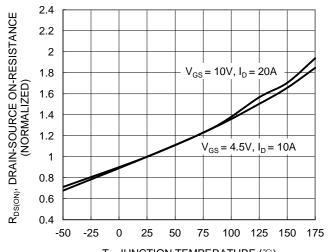


Figure 4. Typical Transfer Characteristic



 $T_{J}, JUNCTION\ TEMPERATURE\ ({}^{\circ}\!\mathbb{C})$  Figure 6. On-Resistance Variation with Temperature





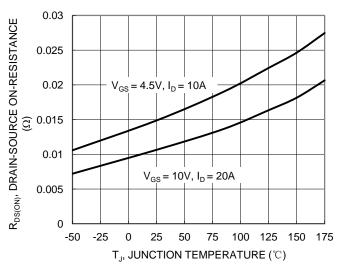
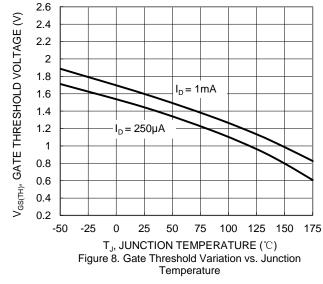


Figure 7. On-Resistance Variation with Temperature



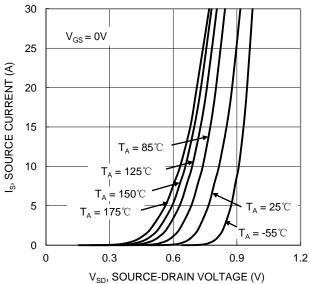


Figure 9. Diode Forward Voltage vs. Current

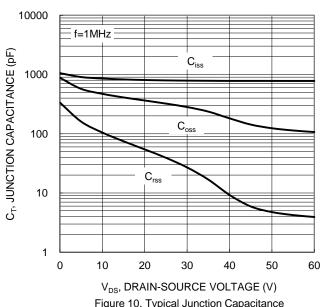
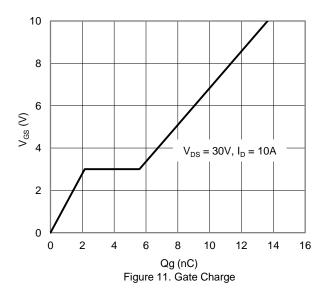


Figure 10. Typical Junction Capacitance



1000 100 ID, DRAIN CURRENT (A) 10 =10μs  $P_W = 10ms$ T<sub>J(Max)</sub> = 175℃ Single Pulse DUT on Infinite Heatsink  $V_{GS} = 10V$ DC 0.01 100 0.1 1 10 1000 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area



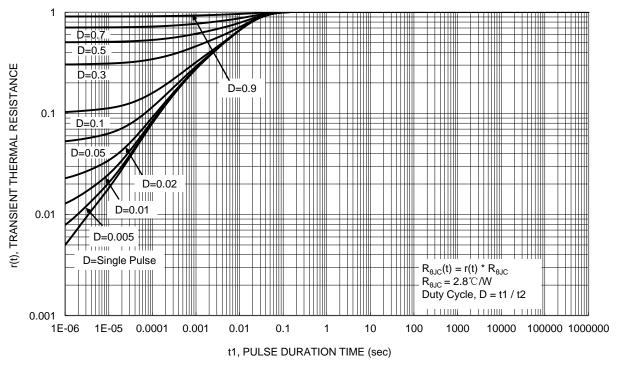


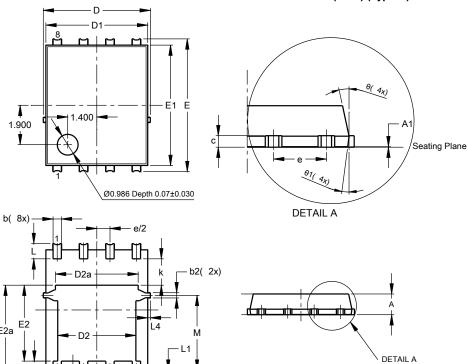
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI5060-8 (SWP) (Type Q)



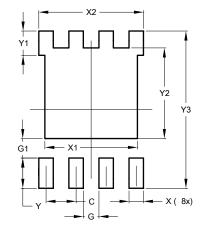
| PowerDI5060-8 (SWP)  |             |         |       |  |  |
|----------------------|-------------|---------|-------|--|--|
|                      | (Type Q)    |         |       |  |  |
| Dim                  | Min         | Max     | Тур   |  |  |
| Α                    | 0.90        | 1.10    | 1.00  |  |  |
| A1                   | 0           | 0.05    | -     |  |  |
| b                    | 0.30        | 0.50    | 0.41  |  |  |
| b2                   | 0.20        | 0.35    | 0.25  |  |  |
| b4                   | (           | ).25REF |       |  |  |
| С                    | 0.230       | 0.330   | 0.277 |  |  |
| D                    |             | .15 BS0 | )     |  |  |
| D1                   | 4.70        | 5.10    | 4.90  |  |  |
| D2                   | 3.56        | 3.96    | 3.76  |  |  |
| D2a                  | 3.78        | 4.18    | 3.98  |  |  |
| Е                    | 6           | .40 BS0 | 2     |  |  |
| E1                   | 5.60        | 6.00    | 5.80  |  |  |
| E2                   | 3.46        | 3.86    | 3.66  |  |  |
| E2a                  | 4.195       | 4.595   | 4.395 |  |  |
| е                    | 1           | .27BSC  | )     |  |  |
| k                    | 1.05        |         |       |  |  |
| L                    | 0.635       | 0.835   | 0.735 |  |  |
| La                   | 0.635       | 0.835   | 0.735 |  |  |
| L1                   | 0.200 0.400 |         | 0.300 |  |  |
| L1a                  | 0.050REF    |         |       |  |  |
| L4                   | 0.025       | 0.225   | 0.125 |  |  |
| М                    | 3.205       | 4.005   | 3.605 |  |  |
| θ                    | 10°         | 12°     | 11°   |  |  |
| θ1                   | 6°          | 8°      | 7°    |  |  |
| All Dimensions in mm |             |         |       |  |  |

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

b4( 8x)

### PowerDI5060-8 (SWP) (Type Q)



| Dimensions | Value<br>(in mm) |  |  |
|------------|------------------|--|--|
| С          | 1.270            |  |  |
| G          | 0.660            |  |  |
| G1         | 0.820            |  |  |
| Х          | 0.610            |  |  |
| X1         | 4.100            |  |  |
| X2         | 4.420            |  |  |
| Y          | 1.270            |  |  |
| Y1         | 1.020            |  |  |
| Y2         | 3.810            |  |  |
| Y3         | 6.610            |  |  |



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